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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

application of

Confirmation No. 2562

Daisuke SAKURAI et al.

Docket No. 2003 1517A

Serial No. 10/694,347

Group Art Unit 2822

Filed October 28, 2003 :

MANUFACTURING METHOD FOR ELECTRONIC
COMPONENT-MOUNTED COMPONENT,
MANUFACTURING METHOD FOR ELECTRONIC
COMPONENT-MOUNTED COMPLETED
PRODUCT WITH THE ELECTRONIC
COMPONENT-MOUNTED COMPONENT,
AND ELECTRONIC COMPONENT-MOUNTED
COMPLETED PRODUCT

THE COMMISSIONER IS AUTHORIZED TO CHARGE ANY DEFICIENCY IN THE FEES FOR THIS PAPER TO DEPOSIT ACCOUNT NO. 23-0975

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Pursuant to the provisions of 37 CFR 1.56, 1.97 and 1.98, Applicants request consideration of the reference listed on attached form PTO-1449. A legible copy of the reference listed on the form PTO-1449 is enclosed.

1a. [X] This Information Disclosure Statement is submitted:

within three months of the filing date (or of entry into the National Stage) of the above-entitled application, or

before the mailing of a first Office Action on the merits or the mailing of a first Office Action after the filing of an RCE,

and thus no certification and/or fee is required.

1b. [] This Information Disclosure Statement is submitted

after the events of above paragraph 1a and prior to the mailing date of a final Office Action or a Notice of Allowance or an action which otherwise closes prosecution in the application, and thus:

- (1) [] the certification of paragraph 2 below is provided, or
- (2) [] the fee of \$180.00 specified in 37 CFR 1.17(p) is enclosed.
- 1c. [] This Information Disclosure Statement is submitted:

after the mailing date of a final Office Action or Notice of Allowance or action which otherwise closes prosecution in the application, and prior to payment of the issue fee, and thus:

the certification of paragraph 2 below is provided, and

the fee of \$180.00 specified in 37 CFR 1.17(p) is enclosed.

- 2. It is hereby certified
 - a. [] that each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Statement, or
 - b. [] that no item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application and, to the knowledge of the person signing the certification after making reasonable inquiry, was known to any individual designated in §1.56(c) more than three months prior to the filing of the Statement.
- 3. [] Consideration of the following list of additional information (including any copending or abandoned U.S. application, prior uses and/or sales, etc.) is requested.
- 4. For each non-English language reference listed on the attached form PTO-1449, reference is made to:

- a. [] a full or partial English language translation submitted herewith,
- b. [] a foreign patent office search report (in the English language) submitted herewith,
- c. [X] the concise explanation contained in the specification of the present application at page $\underline{4}$,
- d. [] the concise explanation set forth in the attached English language abstract,
- e. [] the concise explanation set forth below or on a separate sheet attached to the reference:
- 5. [] A foreign patent office search report citing one or more of the references is enclosed.

Respectfully submitted,

Daisuke SAKURAI et al.

By

Michael S. Huppert Registration No. 40,268 Attorney for Applicants

MSH/kjf Washington, D.C. 20006-1021 Telephone (202) 721-8200 Facsimile (202) 721-8250 February 9, 2004

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| PATENT AND TRADEMARK OFFICE LIST OF REFERENCES CITED BY APPLICANT(S) | | | | APPLICANT Daisuke SAKURAI et al. | | | | | | | |
| (Use several sheets if necessary) Date Submitted to PTO: February 9, 2004 | | | | FILING DATE October 28, 2003 | | | | GROUP 2822 | | | |
| U.S. PATENT DOCUMENTS | | | | | | | | | | | |
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| | AO | Shingo SATO et al., entitled " <u>BOARD RELIABILITY OF CERAMIC CSP BY VARIOUS KINDS OF SOLDER MATERIAL</u> ", at a symposium on "Microjoints and Assembly Technology in Electronics" on February 4-5, 1999, page 133. | | | | | | | | | |
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